

L Number	Hits	Search Text	DB	Time stamp
1	2490	silicon with \$6spring\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:33
2	515	(silicon with \$6spring\$1).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:24
3	4	((micromachin\$3 or micro-machin\$3) adj spring\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:34
4	2	((micromachin\$3 or micro-machin\$3) adj spring\$1).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:34
5	3	((micromachin\$3 or micro-machin\$3) adj spring\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:34
6	123	((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ti.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ab.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).clm.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).clm.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ab.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:38
7	341	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:39
8	386	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:40
9	407	(microspring\$1 or micro-spring\$1 or ((MEMS or micromechanical or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((MEMS or micromechanical or micro-mechanical) adj flexure\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 16:40
10	386	(microspring\$1 or micro-spring\$1 or ((MEMS or micromechanical or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((MEMS or micromechanical or micro-mechanical) adj flexure\$1)) and (v-shaped or x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:44
11	2478	(accelerometer\$1 or transducer\$1) and (v-shaped or x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:03

12	250	(accelerometer\$1 or transducer\$1).ti. and (v-shaped or x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:04
13	22	(accelerometer\$1 or transducer\$1).ti. and (v-shaped or x-shaped) and (wafer\$1 or silicon).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:08
14	0	(MEMS).ti. and (v-shaped or x-shaped) and ((wafer\$1 or silicon) with (joining or bonding)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:10
15	18	(MEMS).ti. and ((wafer\$1 or silicon) with (joining or bonding)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:20
16	0	(spring-mass or spring\$1mass).ab. and ((wafer\$1 or silicon) with (joining or bonding)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:20
17	3	(spring-mass or spring\$1mass).ab. and (wafer\$1 or silicon).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:21
18	299	(spring-mass or spring\$1mass).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:21
20	396	(microspring\$1 or micro-spring\$1 or ((MEMS or micromechanical or micro\$1machined or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj flexure\$1)) and (x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:48
21	2	(microspring\$1 or micro-spring\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj spring\$1)).ti. and (x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:48
24	10	(microflexure\$1 or micro-flexure\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj flexure\$1)) and (x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:50
25	99	((microspring\$1 or micro-spring\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj flexure\$1))) and (x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:52
23	90	(microspring\$1 or micro-spring\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj spring\$1)) and (x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:51

26	105	((microspring\$1 or micro-spring\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj spring\$1)) or (microflexure\$1 or micro-flexure\$1 or ((torsion\$2 or MEMS or micromechanical or micro\$1machined or micro-mechanical) adj flexure\$1))) and (x adj shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 17:52
-	14	(torsion adj spring\$1).ti. and (wafer\$1 or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:22
-	2	(torsion adj spring\$1).ti. and micromechanical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:23
-	1	(torsion adj spring\$1).ti. and micro-mechanical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:23
-	20	(torsion adj spring\$1).ti. and (v-shaped or x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:39
-	4	(micromechanical adj spring\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:25
-	2403	(torsion adj spring\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:28
-	757	(216/2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:46
-	21	((torsion adj spring\$1) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:27
-	103	((216/2).CCLS.) and (spring or torsion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:37
-	134	(torsion adj spring\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:37
-	334	(267/154).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:37
-	1	((267/154).CCLS.) and (silicon or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:37
-	223	flexure and (silicon or wafer\$1) and (v-shaped or x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 19:39

-	1	flexure.ti. and (silicon or wafer\$1) and (v-shaped or x-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:39
-	651	(216/24).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:46
-	21	((216/24).CCLS.) and torsion\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:49
-	78	(MEMS and (torsion\$2 or flexure\$1)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:52
-	2552	(MEMS and (torsion\$2 or flexure\$1 or spring\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:11
-	130	MEMS and (torsion\$2 or flexure\$1 or spring\$1) and etch\$3 and (x-shaped or v-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:56
-	968	MEMS and (torsion\$2 or flexure\$1 or spring\$1) and etch\$3 and (mirror or micromirror or microstructure or micromechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:59
-	496	(73/504.12).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:59
-	130	(73/504.14).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 19:59
-	721	MEMS and (torsion\$2 or flexure\$1 or spring\$1) and etch\$3 and (mirror or micromirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:21
-	19	MEMS and (torsion\$2 or flexure\$1 or spring\$1).ti. and etch\$3 and (mirror or micromirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:01
-	324	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:28
-	324	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ti	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:03
-	29	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:03

-	76	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:03
-	38	(microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:08
-	114	((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ti.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ab.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:09
-	3	(microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:08
-	8	(microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:09
-	7	(microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:09
-	48	((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ti.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ab.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).clm.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).clm.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ab.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ti.)) and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:10
-	56	((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ti.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).ab.) or ((microspring\$1 or micro-spring\$1 or ((micromechanical or micro-mechanical) adj spring\$1)).clm.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).clm.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ab.) or ((microflexure\$1 or micro-flexure\$1 or ((micromechanical or micro-mechanical) adj flexure\$1)).ti.)) and (silicon or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:10
-	14	(MEMS and (torsion\$2 or flexure\$1 or spring\$1)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/20 20:11

-	126	(MEMS and (torsion\$2 or flexure\$1 or spring\$1)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:11
-	128	(MEMS and (torsion\$2 or flexure\$1 or spring\$1)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:11
-	222	((MEMS and (torsion\$2 or flexure\$1 or spring\$1)).clm.) or ((MEMS and (torsion\$2 or flexure\$1 or spring\$1)).ab.) or ((MEMS and (torsion\$2 or flexure\$1 or spring\$1)).ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/20 20:12
-	2	(torsion adj spring\$1).ti. and etch\$3 and (wafer\$1 or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:24
-	4	(torsion adj spring\$1).ti. and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:23
-	130	(suspension).ti. and etch\$3 and (wafer\$1 or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:24
-	134	(\$7suspension).ti. and etch\$3 and (wafer\$1 or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:25
-	233	(slider).ti. and etch\$3 and (wafer\$1 or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:26
-	2	(slider).ti. and etch\$3 and (wafer\$1 or silicon) and (x-shaped or v-shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:26
-	20	MEMS adj spring\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/24 16:23